"GullWing Chip" Sockets

Screw-, Fast-, QuickLock & ClamShell Type



ScrewLock Type



GullWing sockets are available for any GullWing type chips (QFP, PQFP, SOIC, SO etc.) and lead pattern. The sockets are available for any pin-out and tip-to-tip dimension as of 0.50mm pitch upwards. The SMT socket is simply placed and reflowed onto the PCB in the same way as the chip and it only requires a small amount of additional board space. The standard locking system is the ScrewLock design, but QuickLock and ClamShell locking systems are also available.

We aim to solve your requirements - many different terminals and configurations are available.

Your custom sets our standards!

SMT style

Ø 0.50mm/.020" if pitch 1.27mm

Ø 0,50mm/.020" if pitch 1,00mm

Ø 0,40mm/.016" if pitch 0,80mm

Ø 0,35mm/.014" if pitch 0,75mm

Ø 0,35mm/.014" if pitch 0,65mm

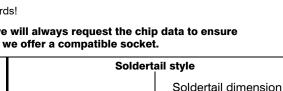
PCB Pad Layout

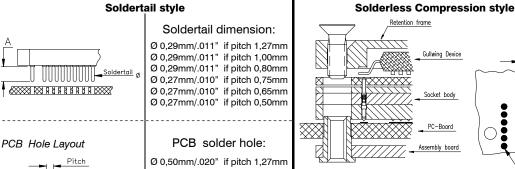
solder pad

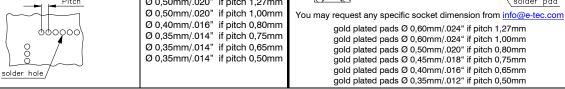
Pitch

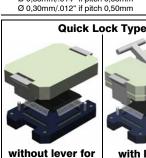
optional locating peg

Please note, we will always request the chip data to ensure









low leadcount chips



with lever for high leadcount chips

FastLock Type

adapted to low and high leadcount chips

ClamShell Type

with center screw for high leadcount chips

Recommendations:

Solder paste - Please use a solder paste w/o any silver! Solder profile - Please refer to our website www.e-tec.com

E-tec solderless sockets are adapted to a standard PCB thickness of 1.60mm. For a different PCB thickness, please inform E-tec first!

The SMT sockets are mounted with straight SMT pins (not bent legs), which are adapted to round PCB pads. For rectangular PCB pads, please ensure that the round socket pins will be surface mountable, since E-tec cannot offer any guarantee in such instances.

For SMT sockets in general, E-tec recommends the use of locating pegs, which can be soldered to the PCB for added mechanical strength.

Specifications

Gullwing Device

Socket body

PC-Board

Assembly board

Mechanical data

Contact life Retention System life

ScrewLock & FastLock QuickLock & ClamShell

Solderability Individual contact force

Material

Insulator (RoHS compliant) (RoHS compliant) Terminal Contact (RoHS compliant)

Electrical data

Contact resistance Current rating

Inductance

Insulation resistance at 500V DC

Breakdown voltage at 60 Hz Capacitance

Operating temperature

10.000 cycles min.

1.000 cycles min. 10.000 cycles min. as per IÉC 60068-2-58 40 grams max.

High temp plastic or epoxy FR4 Brass BeCu

 $< 100 \text{ m}\Omega$

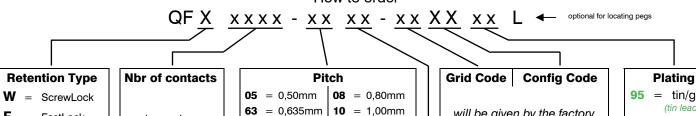
500 mA max

100 M Ω if 0.50 to 0.80mm pitch 500 M Ω 1.00mm pitch upwards 500V min.

< 1 pF

-55°C to +125°C; 260°C for 60 sec.

How to order



FastLock QuickLock

ClamShell

depends on leadcount of chip 06 = 0.65 mm12 = 1,27mm 07 = 0.75mm

others on request

will be given by the factory after receipt of the chip datasheet

95 = tin/gold(tin leadfree) 55 = goldonly for solderless Compression Type

Contact Type

30 = standard SMT....("A" = 0,80mm if 1,27mm pitch or 1,00mm pitch, 0.60 if 0,80mm pitch; 0,40mm if <0.80mm pitch)

29 = raised SMT...("A" = 3,20mm if 1,27mm pitch or 1,00mm pitch; 2,80mm if 0,80mm pitch, 2.30mm if <0.80mm pitch)

28 = special raised SMT - only for 1,27, 1.00 & 0.80mm pitch......("A" = 4,50mm)

70 standard solder tail......(, $_{n}$ $^{\mu}$ = 2,80 if 1.27mm pitch, 1.00mm or 0.80mm pitch; 2,30mm if <0.80mm pitch)

90 = solderless Compression Type